REMARKS

This is in response to the final Office Action dated January 7, 2009, and is respectfully submitted to be fully responsive to the rejections raised therein. Accordingly, favorable reconsideration on the merits and allowance are respectfully requested. Claims 1 and 3-7 are all the claims pending in the application.

Response to Rejection

Claims 1 and 3-7 are rejected under 35 U.S.C. § 103(a) as assertedly being unpatentable over JP 05-302026 (Toda) in view of JP 05-059267 (Watabe).

Applicant respectfully traverses and requests that the rejection be withdrawn in view of the remarks as set forth in the Amendment filed November 25, 2008 and in view of the additional remarks below.

Applicant submits that Toda and Watabe are directed to sealing materials. The composition described in Toda is used for a sealing material, and as such, the composition does not require a high adhesive strength. See Toda at paragraph [0001]. If the composition in Toda has too much adhesive strength, it may adversely cause pollution to form on the substrate. The curable composition in Toda comprises (a) a polymer having a main chain essentially consisting of a polyether and terminated with a cross-linkable hydrolyzable silyl group, (b) a resin, such as a rosin ester resin, and (c) a curing catalyst. The Examiner concedes that Toda does not teach the addition of an oxyalkylene polymer, which corresponds to component (B) of the presently claimed composition.

Applicant respectfully submits that the compositions in Toda are comparable to the compositions in Comparative Examples 1 and 2 of the present application. Namely, the

compositions in Comparative Examples 1 and 2 do not contain a hydrolysable silyl group-containing organic polymer containing 0.3 to 1.3 hydrolyzable silyl groups per molecule and having a number average molecular weight of 500 to 15, 000, the main chain of which polymer being substantially composed of a repeating unit or units represented by the general formula $-R^1-O-$ (R^1 being a divalent alkylene group); i.e., present component (B).

Particularly, in Comparative Example 1, as described in the present application, 50 weight parts of tackifier resin is used, but the adhesive strength of the compositon is only 7.6 N/25 mm. In Comparative Example 2, the amount of tackifier resin used is as large as 100 weight parts, but the adhesive strength of the composition is only 10.2 N/25 mm. The results in Table 1 indicate that the addition of even a large amount of tackifier resin does not improve adhesive strength of the composition. Comparative Example 2 uses toluene to reduce the viscosity of the composition which was increased by a large amount of tackifier resin. However, the addition of toluene does not effect the adhesive strength.

The pressure sensitive adhesive product of the present invention is obtained by curing the pressure sensitive adhesive composition comprising the components (A), (B) and (C), as recited in claim 1. Specifically, combining component (B) with component (A) achieves a very high adhesive strength. Therefore, a large amount of tackifier resin is not required and a highly viscous composition can be prevented.

Applicant further submits that the adhesive strength triples or quadruples when component (B) is present in the composition; as can be seen in Examples 1 or 2 compared with Comparative Example 1 of the present application.

Applicant submits that although components may look superficially similar, the pressure sensitive adhesive composition obtained in the present claimed invention is very different from the composition that is obtained for the sealing material in Toda.

The object of the presently claimed invention is to resolve problems unique to pressure sensitive adhesive compositions. Namely, the object of the present claimed invention is to improve the adhesive strength and to control the viscosity of the composition. These features are not material to sealing materials as described in Toda and Watabe. The inventions in Toda and Watabe are related to a sealing material and do not have these problems.

Watabe teaches the use of a low molecular weight compound (II), as a plasticizer to obtain a sealing material which has a low transitivity (low degree of weight decrease). Compound (II) in Watabe is analogous to component (B) in the presently claimed composition. However, Applicant respectfully submits that it is unpredictable from Watabe that a combination of components (A) and (B) can improve the adhesive strength, reduce the amount of tackifier resin, and thus, reduce the amount of solvent used in the composition.

The presently claimed invention is not rendered obvious by the Toda, either alone or in combination with Watabe. Accordingly, Applicant respectfully request that the rejection of claims 1 and 3-7 be withdrawn.

II. Conclusion

In view of the above, reconsideration and allowance of claims 1 and 3-7 of this application are now believed to be in order, and such actions are hereby earnestly solicited.

If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned attorney at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

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